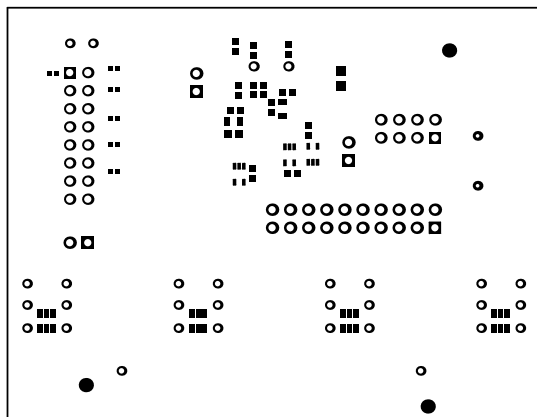
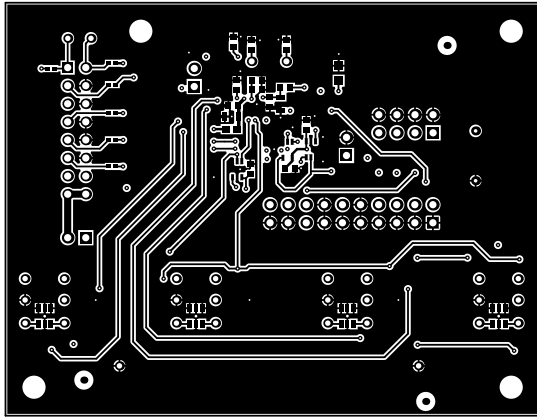


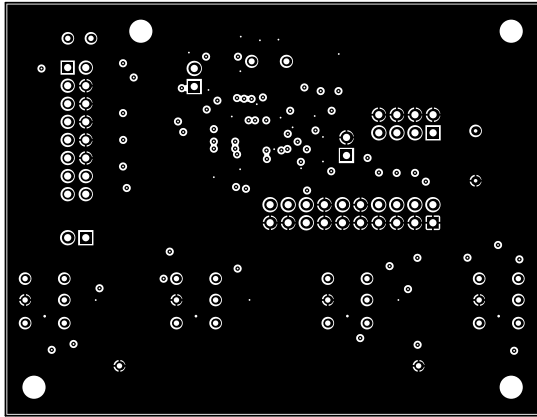
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01470	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top SilkScreen			
PLOT NAME = Top Silkscreen	GENERATED : 5/12/2017 10:59:40 AM	TEXAS INSTRUMENTS	



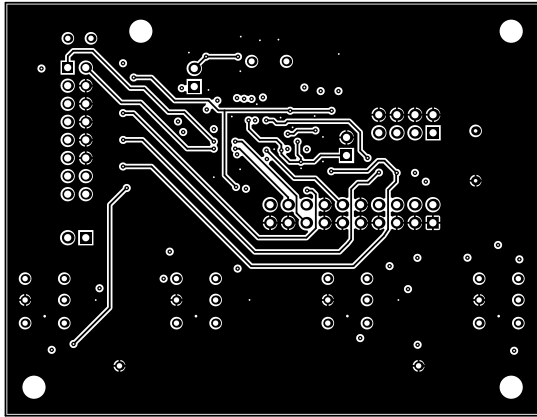
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01470	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder Mask			
PLOT NAME = Top SolderMask	GENERATED : 5/12/2017 10:59:41 AM	TEXAS INSTRUMENTS	



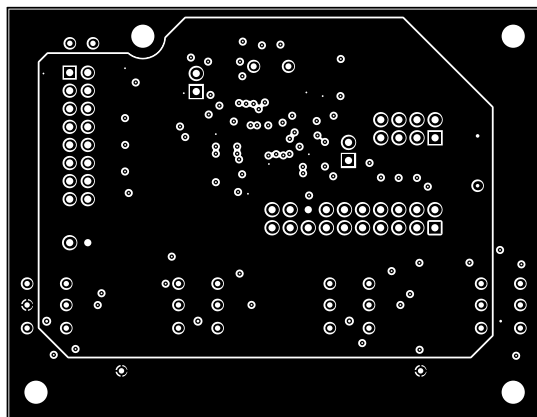
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01470	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Copper			
PLOT NAME = Top Copper	GENERATED : 5/12/2017 10:59:42 AM	TEXAS INSTRUMENTS	



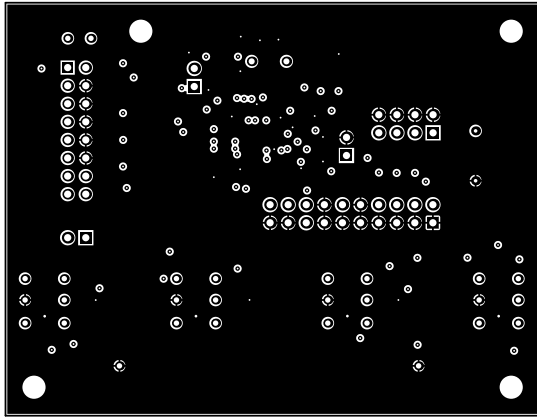
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01470	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Copper Layer 2			
PLOT NAME = Copper Layer 2	GENERATED : 5/12/2017 10:59:43 AM	TEXAS INSTRUMENTS	



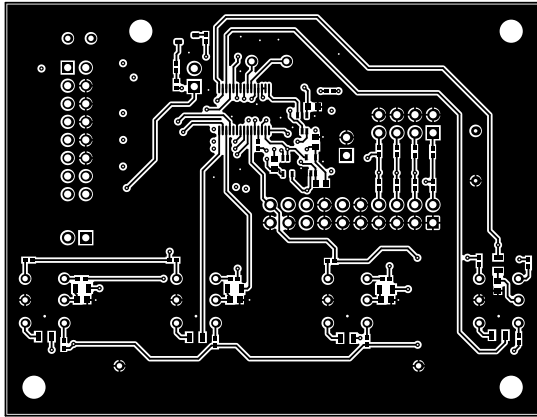
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01470	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Copper Layer 3			
PLOT NAME = Copper Layer 3	GENERATED : 5/12/2017 10:59:43 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01470	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Copper Layer 4			
PLOT NAME = Copper Layer 4	GENERATED : 5/12/2017 10:59:44 AM	TEXAS INSTRUMENTS	

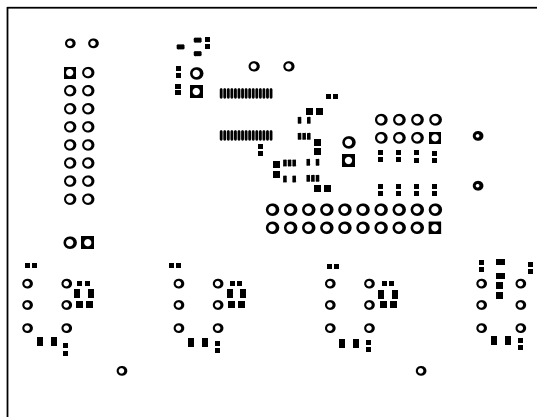


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01470	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Copper Layer 5			
PLOT NAME = Copper Layer 5	GENERATED : 5/12/2017 10:59:45 AM	TEXAS INSTRUMENTS	

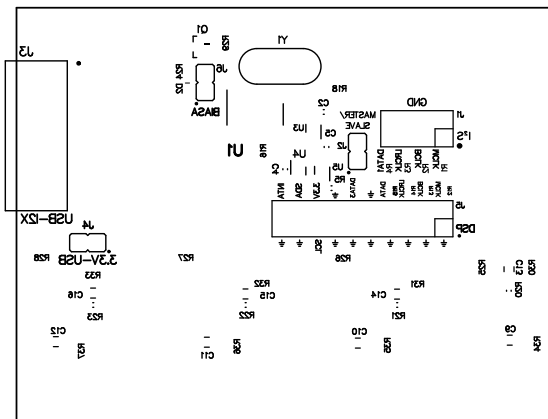


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01470	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Copper			
PLOT NAME = Bottom Copper	GENERATED : 5/12/2017 10:59:46 AM	TEXAS INSTRUMENTS	

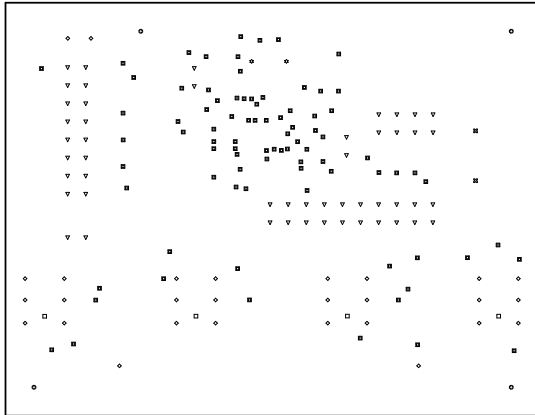




ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01470	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder Mask			
PLOT NAME = Bottom SolderMask	GENERATED : 5/12/2017 10:59:47 AM	TEXAS INSTRUMENTS	

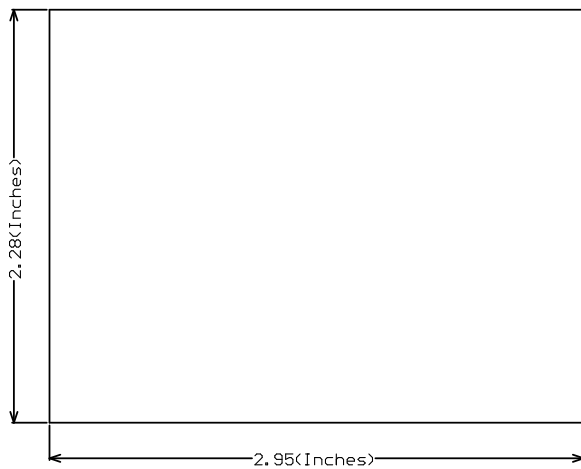


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01470	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Silk			
PLOT NAME = Bottom Silk	GENERATED : 5/12/2017 10:59:48 AM	TEXAS INSTRUMENTS	



Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template	Description	Hole Tolerance (+)	Hole Tolerance (-)
⊗	2	0.508mm (20.00mil)	PTH	Round	Top Copper - Bottom Copper	Pad	Rounded	c127h51			
⊙	2	0.850mm (33.46mil)	PTH	Round	Top Copper - Bottom Copper	Pad	Rounded	c135h85			
□	4	0.381mm (15.00mil)	PTH	Round	Top Copper - Bottom Copper	Via	Rounded	v76h38m0mx0			
⊕	4	3.250mm (127.95mil)	PTH	Round	Top Copper - Bottom Copper	Via	Rounded	v600h325m0mx0			
◇	28	0.762mm (30.00mil)	PTH	Round	Top Copper - Bottom Copper	Pad	Rounded	c127h76			
▽	50	1.016mm (40.00mil)	PTH	Round	Top Copper - Bottom Copper	Pad	(Mixed)	(Mixed)			
■	86	0.254mm (10.00mil)	PTH	Round	Top Copper - Bottom Copper	Via	Rounded	v64h25m0mx0			
	176 Total										

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01470	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 5/12/2017 10:59:49 AM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01470	REV: A	SUN REV: Not In VersionControl
LAYER NAME =	M2 Board Dimensions		
PLOT NAME = Board Dimensions	GENERATED : 5/12/2017	10:59:51 AM	TEXAS INSTRUMENTS

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